

RECOMMENDED MOUNTING METHOD

Soldering Methods, Recommended Soldering Method for Moisture-Proof Packing and Flux Cleaning are in the following.

Mounting was evaluated with the following profiles in our company, so there was no problem. However, confirm mounting by the condition of your company beforehand.

BIPOLAR, C-MOS, GaAs

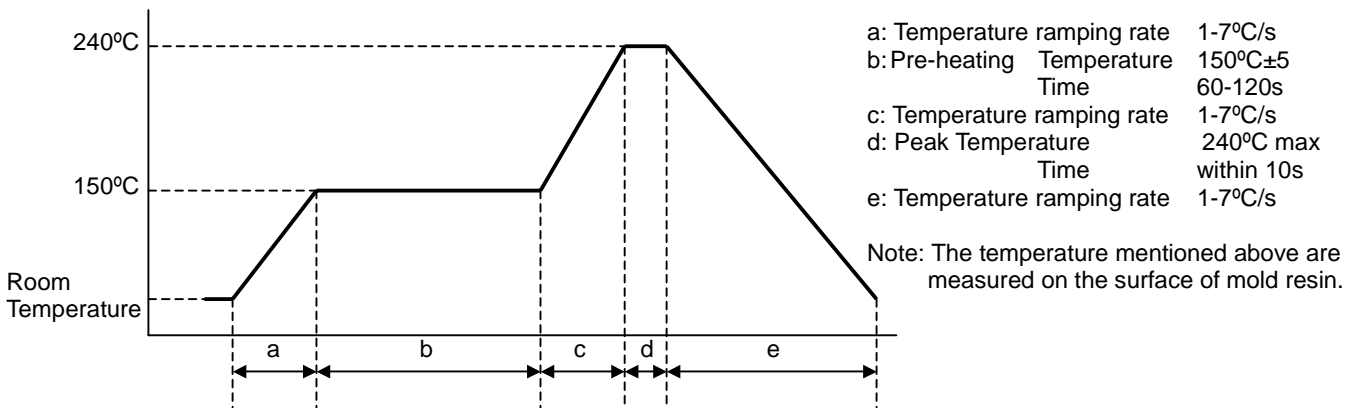
1. Soldering Methods

The recommended soldering methods are in the following.

(1) Standard Products

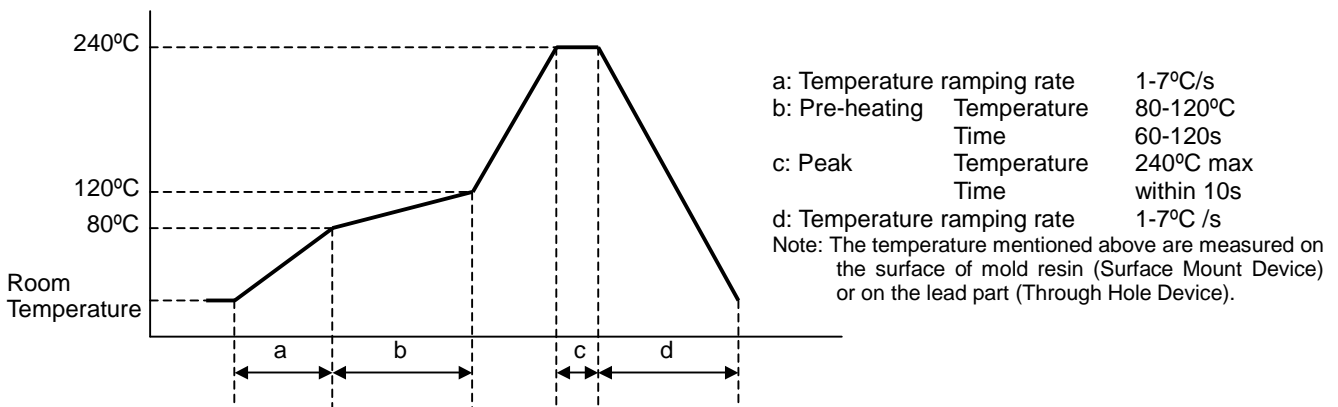
1) Soldering Temperature Profile of Reflow

Recommended reflow soldering temperature profile is in the following.



2) Soldering Temperature Profile of Flow

Recommended flow soldering temperature profile is in the following.



3) Soldering Temperature Profile of Iron

Recommended iron soldering temperature profile is in the following.

At 1 lead Temperature : within 300 - 340°C
Time : within 3s

4) Note

It is not good for IC's reliability to keep IC high temperature for long time within limit of recommended ranges.

Please finish soldering as soon as possible within limit of recommended ranges.

See the next section, "IC storage Conditions and Duration" for Moisture-Proof Packing and Deaeration Packing.

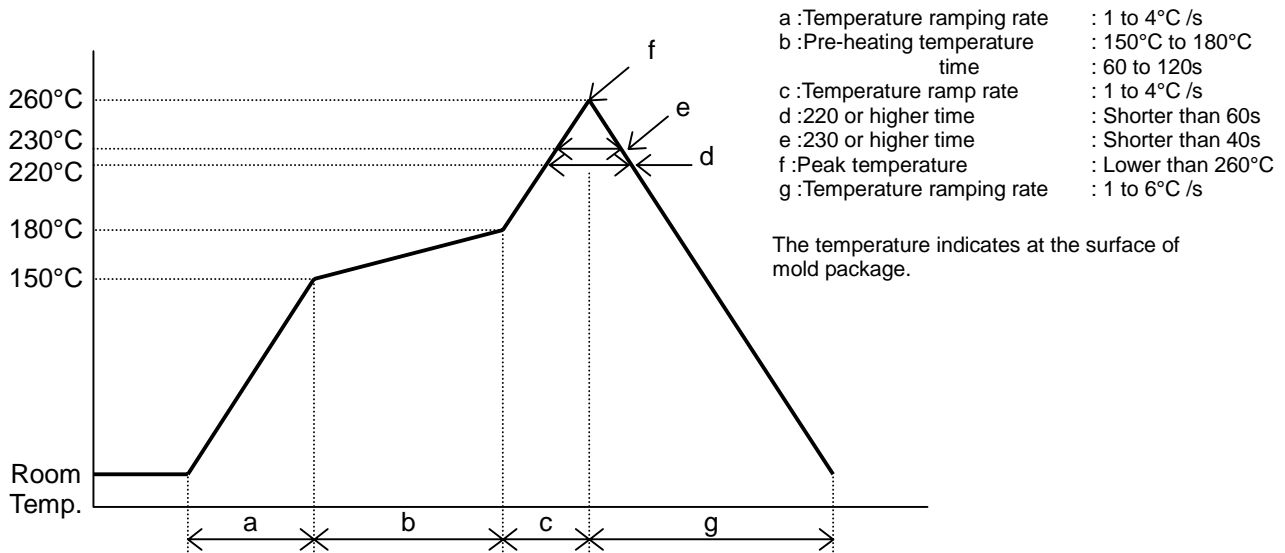
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(2) Lead-Free Products

New JRC is committed to offering lead-free products.
Lead free solutions may vary according to products.
Contact at our local sales reps/agents for further information.

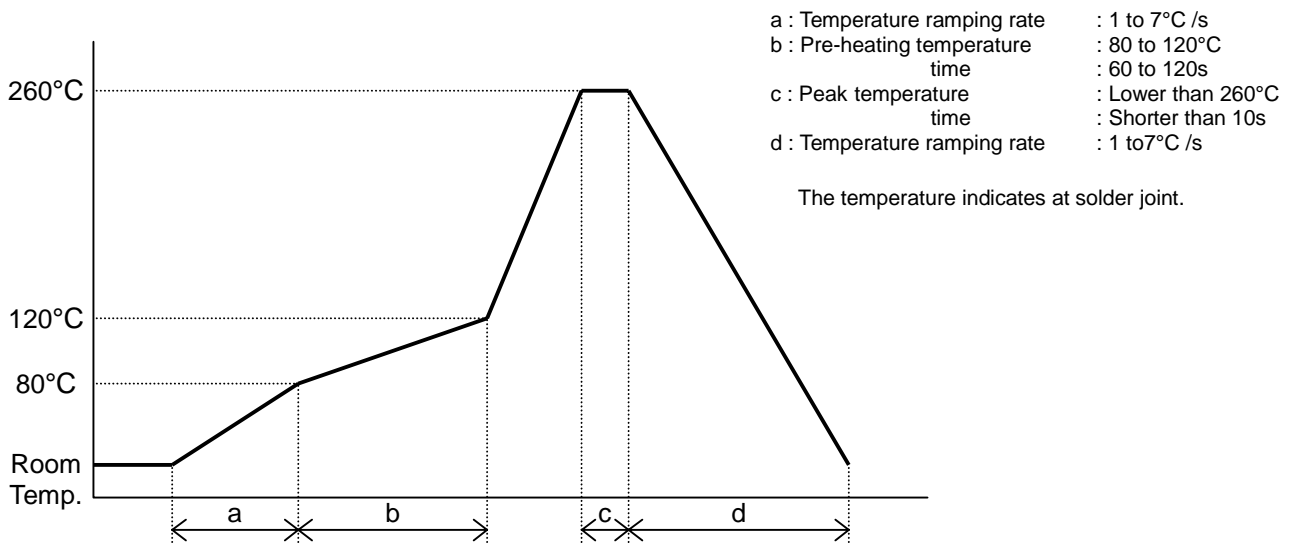
1) Soldering Temperature Profile of Reflow

Recommended reflow soldering temperature profile is in the following.



2) Soldering Temperature Profile of Flow

Recommended flow soldering temperature profile is in the following.



3) Soldering Temperature Profile of Iron

Recommended iron soldering temperature profile is in the following.

At 1 lead Temperature : Lower than 350°C
 Time : within 3s

4) Note

It is not good for IC's reliability to keep IC high temperature for long time within limit of recommended ranges.
Please finish soldering as soon as possible within limit of recommended ranges.
See the next section, "IC storage Conditions and Duration" for Moisture-Proof Packing and Deaeration Packing.

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2. IC Storage Conditions and Duration

It is better to keep IC's at the following condition.

Temperature: 5 - 40 °C, Humidity: 30 (Note) - 75 %

- 1) Do not store the products in the place where the temperature fluctuation frequently occurs; dew may cause critical damage to the products.
- 2) Do not expose the products in the corrosive atmosphere.
- 3) Store the products in dust free place.
- 4) Do not expose the products to a direct sun light.
- 5) Store the IC without adding a load.

Note: Do not store the products in a place where the humidity is below 30 percent: electrostatic discharge may damage the products.

IC Storage Conditions and Duration for Moisture-Proof Packing

1) Mounting

Be sure to use within 7days after opening and to apply 2nd soldering within 3days.

Be sure to apply soldering within twice.

2) Storage

It is better to keep IC's at following condition.

Before unpacking : Temperature: 5 - 40°C, Humidity: within 80%

After unpacking : Temperature: 5 - 25°C, Humidity: 40-60%

3) Baking

In case of keeping except above condition, be sure to apply baking.

Baking Method: Ta=125°C, over 16h

IC Storage Conditions and Duration for Deaeration Packing

1) Mounting

Be sure to apply soldering within one month after opening.

2) Storage

It is better to keep IC's at following condition.

Before unpacking : Temperature: 5 - 40°C, Humidity: 40 - 80%

After unpacking : Temperature: 5 - 40°C, Humidity: 40 - 60%

3. Flux Cleaning

Please clean flux, because halogen compound in flux badly affects the reliability of products. A supersonic cleaning is available and the example of condition is in the following.

Frequency : 28kHz

Power : 20W/l

Temperature : 40°C

Time : between 30 - 60s

CAUTION: Don't rub the marking while cleaning, or the marking may be erased.

Keep the products not to resonate, and not to touch the oscillating element.